

IN THE ABSTRACT:

Please amend the abstract as follows:

A programmed material consolidation apparatus includes a support with a surface that receives at least one substrate and prevents unconsolidated material from contacting undesired regions, such as the bottom surface, of the at least one substrate ~~at least one fabrication site and a material consolidation system associated with the at least one fabrication site.~~ The at least one fabrication site may be configured to receive one or more fabrication substrates, such as semiconductor substrates. A machine vision system with a translatable or locationally fixed camera may be associated with the at least one fabrication site and the material consolidation system. A cleaning component may also be associated with the at least one fabrication site. The cleaning component may share one or more elements with the at least one fabrication site, or may be separate therefrom. The programmed material consolidation apparatus may also include a substrate handling system, which places fabrication substrates at appropriate locations of the programmed material consolidation apparatus. When a programmed material consolidation process is used to form one or more objects on or adjacent to a substrate, the substrate may be secured to a support surface. Additionally, unconsolidated material may be prevented from contacting one or more undesired areas of the substrate.